

WHAT IS CLAIMED IS:

- 1. A method for testing print circuit boards comprising the following steps:**
 - (a) measuring all points to be tested on the print circuit board;**
 - (b) manufacturing a testing board having protrusive metal points according to the information obtained in step (a), the testing board having at least one set of holes for connectors;**
 - (c) connecting the protrusive metal points in step (b) to the connector holes on the testing board;**
 - (d) connecting the testing board having protrusive metal points to a tester and the protruding metal points connected to test node in the tester, and**
 - (e) inserting at least one pressure sensitive conductive rubber layer between the testing board having protruding metal points and the print circuit board to be tested, a pressure from a press of the tester being transferred to the pressure sensitive conductive rubber layer via the protrusive metal points and the points to be tested.**
- 2. The method as claimed in Claim 1, wherein the measurement in step (a) is made by software.**
- 3. The method as claimed in Claim 1, wherein the hole in step (b) is located at a side of the testing board.**
- 4. The method as claimed in Claim 1, wherein coordinates of the metal points in step (b) are the same as those of the points to be tested on the print circuit board.**
- 5. The method as claimed in Claim 1, wherein the connection in step (c) is made by way of layout.**
- 6. The method as claimed in Claim 1, wherein the connection in step (d) is made by flat cables.**

7. The method as claimed in Claim 1, wherein the tester in step (d) is a dedicated tester.
8. A method for testing print circuit boards comprising the following steps:
 - (a) measuring all points to be tested on the printed circuit board;
 - (b) manufacturing a print board having protrusive metal points according to the information obtained in step (a), the print circuit board having at least one hole for connection member;
 - (c) connecting the protrusive metal points in step (b) to the holes on one side of the testing board;
 - (d) connecting the testing board having protrusive metal points to a tester and the protrusive metal points connected to test nodes in the tester, and
 - (e) coating liquid conductive rubber to tip of each metal point and trimming solidified conductive rubber to be in flush with each other, aligning the points to be tested on print circuit board with the protrusive metal points on testing board, using a press of the tester to apply a pressure to the conductive rubber via the protrusive metal points and the points to be tested on the printed circuit board.
9. The method as claimed in Claim 8, wherein the measurement in step (a) is made by software.
10. The method as claimed in Claim 8, wherein the hole in step (b) is located at a side of the print circuit board.
11. The method as claimed in Claim 8, wherein coordinates of the metal points in step (b) are the same as those of the points to be tested on the printed circuit board.
12. The method as claimed in Claim 8, wherein the connection in step (c) is made by way of layout.

- 13.** The method as claimed in Claim 8, wherein the connection in step (d) is made by flat cables.
- 14.** The method as claimed in Claim 8, wherein the tester in step (d) is a dedicated tester.
- 15.** A method for testing print circuit boards comprising the following steps:
- (a) measuring all points to be tested on the print circuit board;
 - (b) manufacturing a print board having protrusive metal points according to the information obtained in step (a), the testing board having at least one set of holes for connectors;
 - (c) connecting the protrusive metal points in step (b) to the holes on the print circuit board;
 - (d) connecting the testing board having protruding metal points to a tester and the protrusive metal points connected to test nodes in the tester, and
 - (e) taping each protruding metal point with a electrically z-axis conductive adhesive film which is conductive in vertical direction, aligning the points to be tested on printed circuit board with the protrusive metal points, using a press of the tester to applying a pressure and flexibility of the conductive rubber to electrically connect the protrusive metal points to the points to be tested on the printed circuit board.
- 16.** The method as claimed in Claim 15, wherein the measurement of step (a) is made by software.
- 17.** The method as claimed in Claim 15, wherein the hole in step (b) is located at a side of the test board.
- 18.** The method as claimed in Claim 15, wherein coordinates of the metal points in step (b) are the same as those of the points to be tested on the printed circuit board.

- 19.** The method as claimed in Claim 15, wherein the connection in step (c) is made by way of layout.
- 20.** The method as claimed in Claim 15, wherein the connection in step (d) is made by flat cables.
- 21.** The method as claimed in Claim 15, wherein the tester in step (d) is a dedicated tester.